

	L #	Hits	Search Text	DBs
1	L1	5453	(343/700ms,702,872,873).ccls.	US-PGPU B; USPA T
2	L2	943	1 and (semiconductor die chip\$1)	US-PGPU B; USPA T
3	L3	481	1 and ((integrated adj circuit) ic)	US-PGPU B; USPA T
4	L4	1155	2 3	US-PGPU B; USPA T
5	L5	990	4 and (board\$1 substrate\$1 ((flexible flex) adj circuit\$1))	US-PGPU B; USPA T
6	L6	856	(257/664,728).ccls.	US-PGPU B; USPA T
7	L7	4584	(361/760,767,768,771,780,782,783,784,803,749,750,751).ccls.	US-PGPU B; USPA T

	L #	Hits	Search Text	DBs
8	L8	307	(6 7) and (antenna\$1 aerial\$1)	US- PGPU B; USPA T
9	L9	980	5 not 8	US- PGPU B; USPA T
10	L10	31	9 and micro\$1electronic	US- PGPU B; USPA T
11	L11	949	9 not 10	US- PGPU B; USPA T
12	L12	97	11 and (bump\$1 ball\$1 (flip adj chip) bga)	US- PGPU B; USPA T
13	L13	852	11 not 12	US- PGPU B; USPA T
14	L14	196	13 and (flex flexible)	US- PGPU B; USPA T

	L #	Hits	Search Text	DBs
15	L15	1	13 and interposer\$1	US- PGPU B; USPA T
16	L16	1	"6335669".pn.	US- PGPU B; USPA T
17	L17	1	16 and ground	US- PGPU B; USPA T